

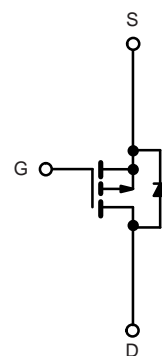
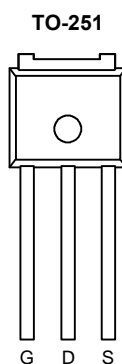
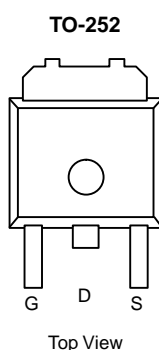
P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^a
- 30	0.0073 at $V_{GS} = - 10$ V	-85
	0.009 at $V_{GS} = - 4.5$ V	-80

FEATURES

- Compliant to RoHS Directive 2002/95/EC


 Available
RoHS*
 COMPLIANT


P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

Parameter	Symbol	Limit	Unit
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_J = 175$ °C)	I_D	$T_C = 25$ °C - 85 ^a	A
		$T_C = 125$ °C - 68	
Pulsed Drain Current	I_{DM}	- 260	
Avalanche Current	I_{AR}	- 67	
Repetitive Avalanche Energy ^b	E_{AR}	186	mJ
Power Dissipation	P_D	$T_C = 25$ °C (TO-220AB and TO-263) 187 ^d	W
		$T_A = 25$ °C (TO-263) ^c 3.75	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Limit	Unit
Junction-to-Ambient	R_{thJA}	PCB Mount (TO-251) ^c 40	°C/W
		Free Air (TO-252) 62.5	
Junction-to-Case	R_{thJC}	0.8	

Notes:

a. Package limited.

 b. Duty cycle ≤ 1 %.

c. When mounted on 1" square PCB (FR-4 material).

d. See SOA curve for voltage derating.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

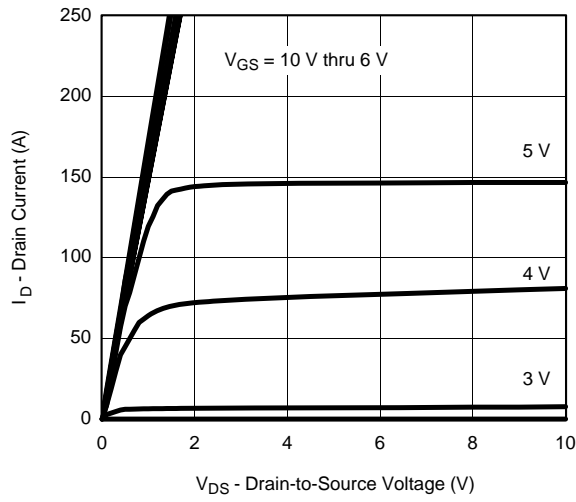
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1		- 3	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 125 °C			- 50	
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 175 °C			- 250	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 30 A		0.0073	0.0082	Ω
		V _{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C			0.0115	
		V _{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C			0.0131	
		V _{GS} = - 4.5 V, I _D = - 20 A		0.009	0.010	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 15 V, I _D = - 75 A	20			S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1 MHz		1089		pF
Output Capacitance	C _{oss}			759		
Reversen Transfer Capacitance	C _{rss}			419		
Total Gate Charge ^c	Q _g	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 75 A		130	280	nC
Gate-Source Charge ^c	Q _{gs}			62		
Gate-Drain Charge ^c	Q _{gd}			39		
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = - 15 V, R _L = 0.2 Ω I _D ≡ - 75 A, V _{GEN} = - 10 V, R _g = 2.5 Ω		25	30	ns
Rise Time ^c	t _r			225	300	
Turn-Off Delay Time ^c	t _{d(off)}			150	210	
Fall Time ^c	t _f			210	290	
Source-Drain Diode Ratings and Characteristics ^b (T _C = 25 °C)						
Continuous Current	I _S				- 85	A
Pulsed Current	I _{SM}				- 260	
Forward Voltage ^a	V _{SD}	I _F = - 75 A, V _{GS} = 0 V		- 1.2	- 1.5	V
Reverse Recovery Time	t _{rr}	I _F = - 75 A, dI/dt = 100 A/μs		55	100	ns
Peak Reverse Recovery Current	I _{RM(REC)}			2.5	5	A
Reverse Recovery Charge	Q _{rr}				0.07	0.25

Notes:

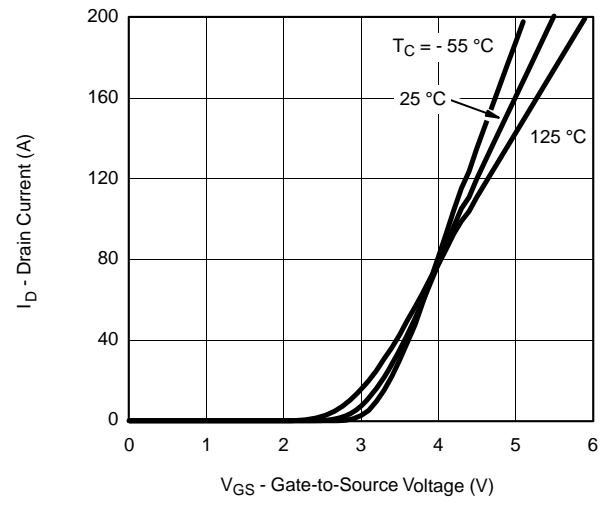
- Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

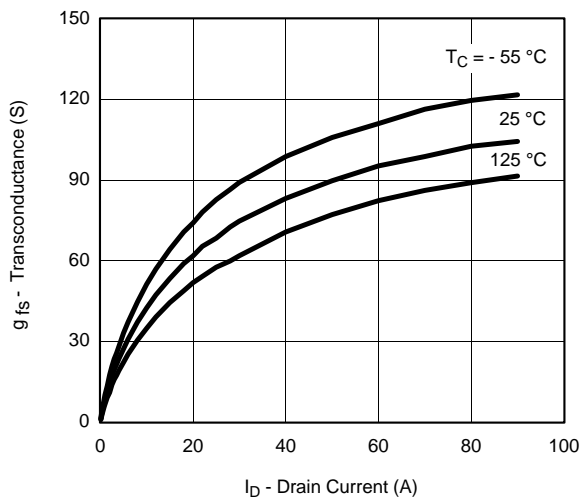
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



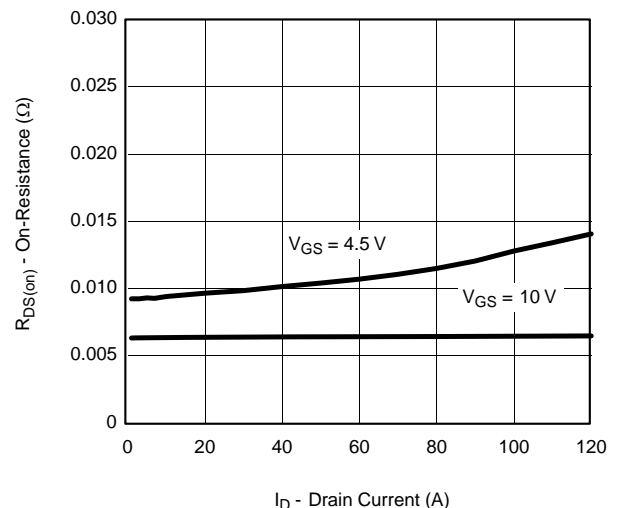
Output Characteristics



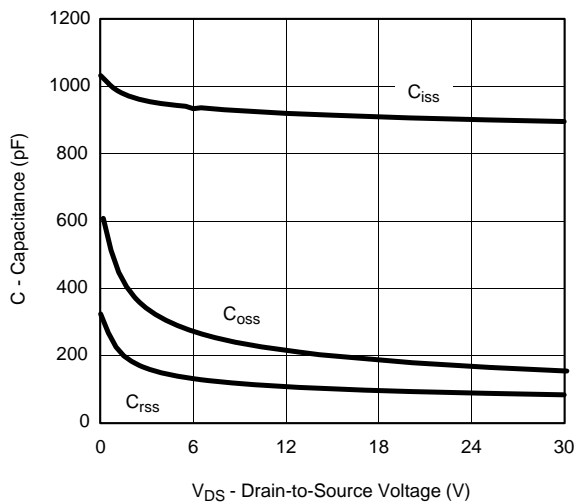
Transfer Characteristics



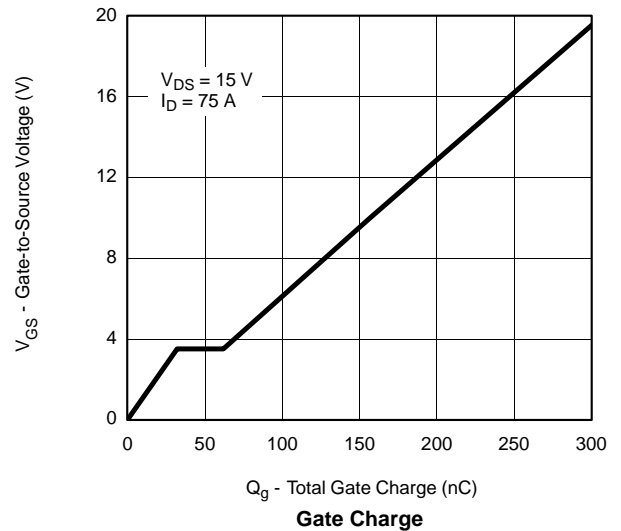
Transconductance



On-Resistance vs. Drain Current

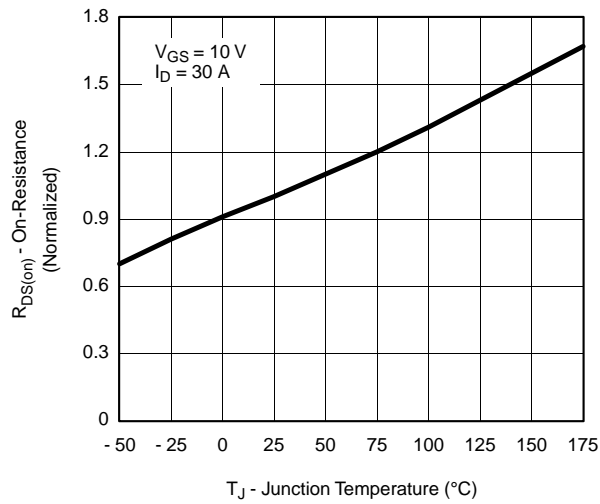


Capacitance

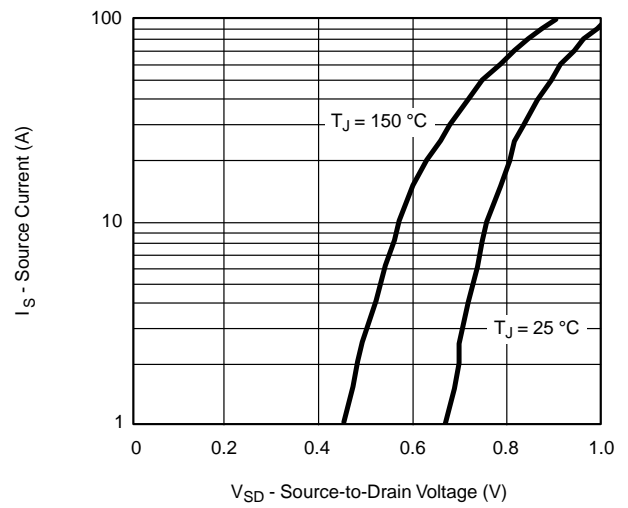


Gate Charge

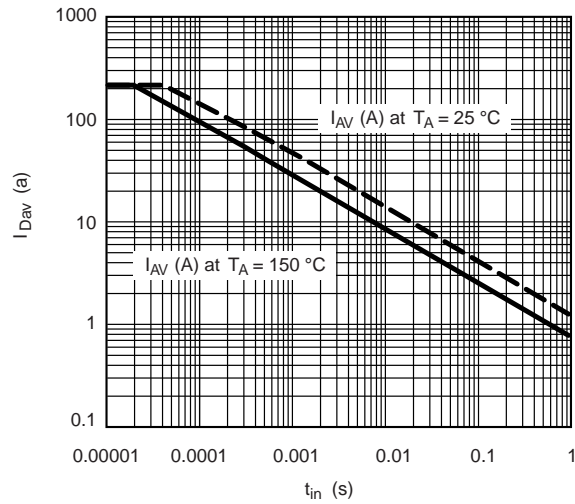
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



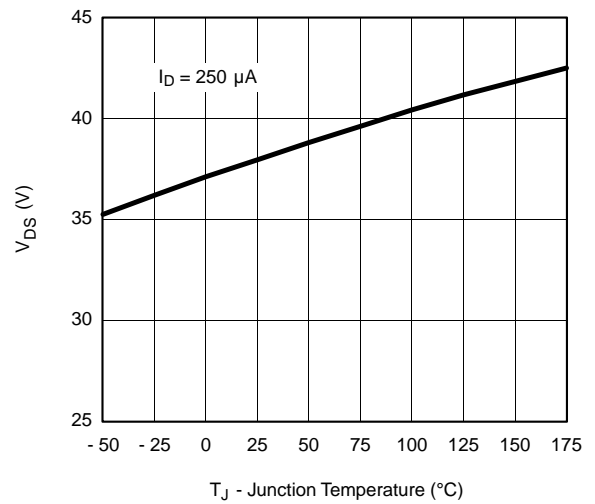
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage

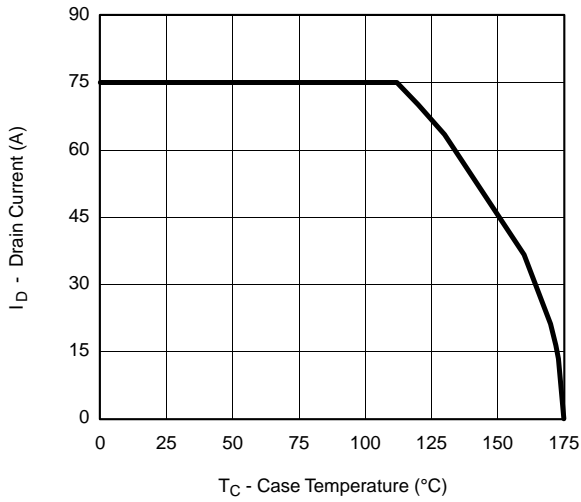


Avalanche Current vs. Time

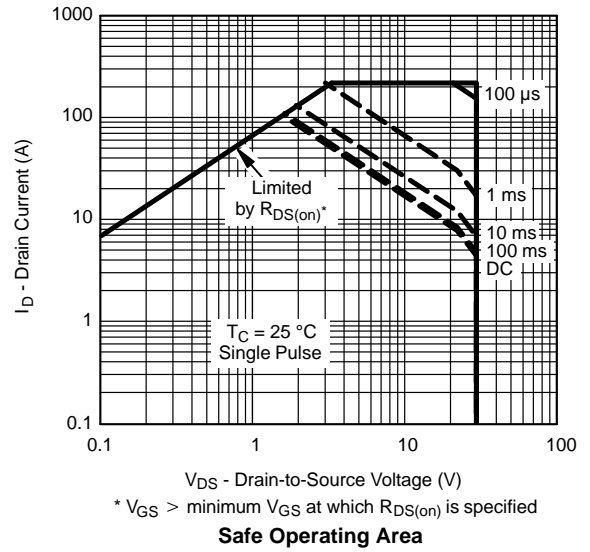


Drain Source Breakdown vs. Junction Temperature

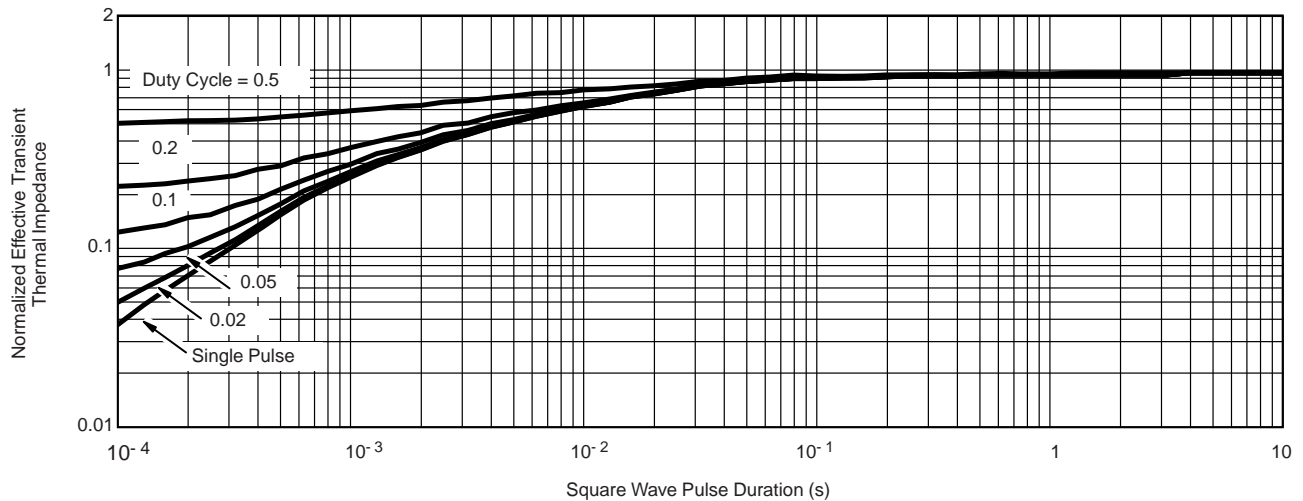
THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature

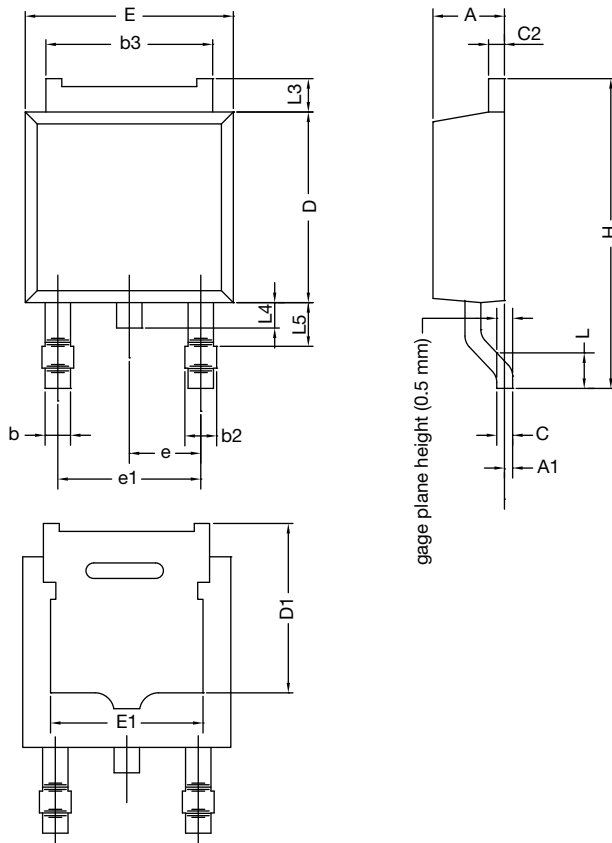


Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

TO-252AA CASE OUTLINE

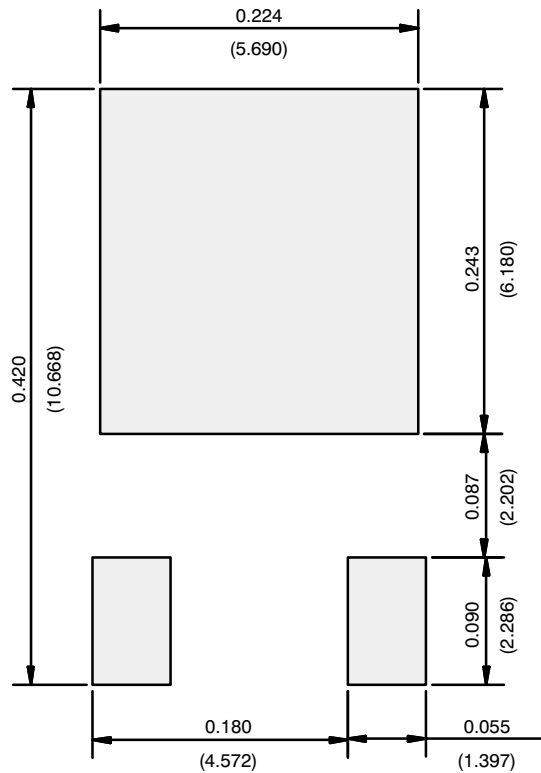


DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
C	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	5.21	-	0.205	-
E	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
H	9.40	10.41	0.370	0.410
e	2.28 BSC		0.090 BSC	
e1	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.14	1.52	0.045	0.060
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347				

Note

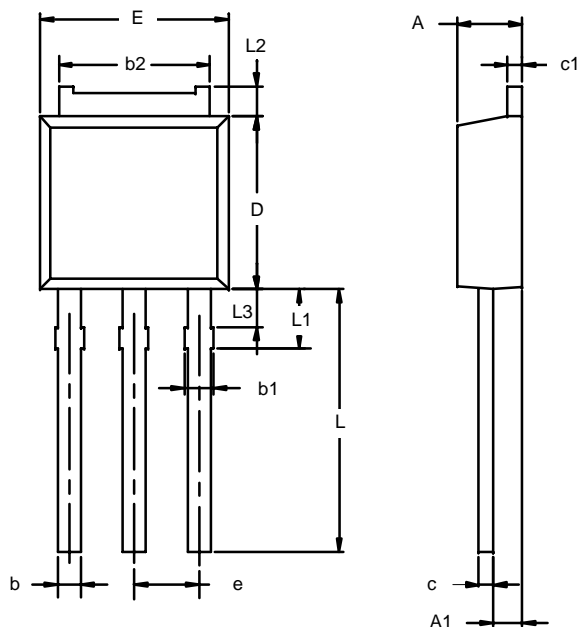
- Dimension L3 is for reference only.

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads
Dimensions in Inches/(mm)

TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
c	0.46	0.58	0.018	0.023
c1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
E	6.48	6.73	0.255	0.265
e	2.28 BSC		0.090 BSC	
L	8.89	9.53	0.350	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346				

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